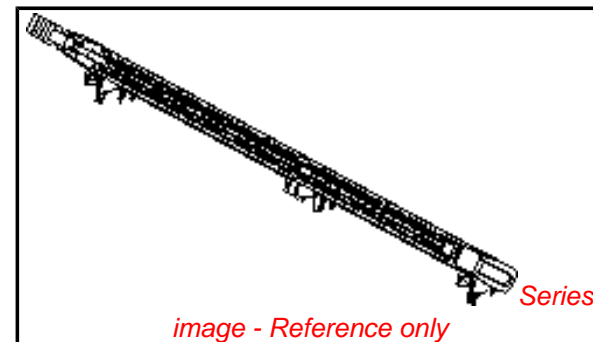


PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0878030002](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR-2 DIMM Socket, 25 Degree Angle, Through Hole, 1.8V Voltage Key, 2.79mm (.110") Tail Length, 0.38µm (15µ") Gold (Au) Plating, 240 Circuits, Lead-free

Documents:

[3D Model](#) [Product Specification PS-87803-003 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)



Agency Certification

CSA LR19980
 UL E29179

General

Product Family Memory Module Sockets
 Series [87803](#)
 Comments No Lubricant at the ContactLatches in Off-White Color
 Component Type Socket
 JEDEC Outline MO-237
 Product Name DDR2 DIMM

Physical

Circuits (Loaded) 240
 Color - Resin Black, Natural
 Durability (mating cycles max) 25
 Entry Angle 25° Angle
 Flammability 94V-0
 Keying to Mating Part Yes
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.110 In
 PC Tail Length (mm) 2.79 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.062 In
 PCB Thickness Recommended (mm) 1.60 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Plating min: Mating (µin) 15
 Plating min: Mating (µm) 0.38
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 0.5A
 Voltage - Maximum 30V AC (RMS)/DC
 Voltage Key 1.8V, Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
 Lead-free Process Capability SMC & Wave Capable (TH only)

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[87803Series](#)

Mates With
 JEDEC standard 1.27mm modules

Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

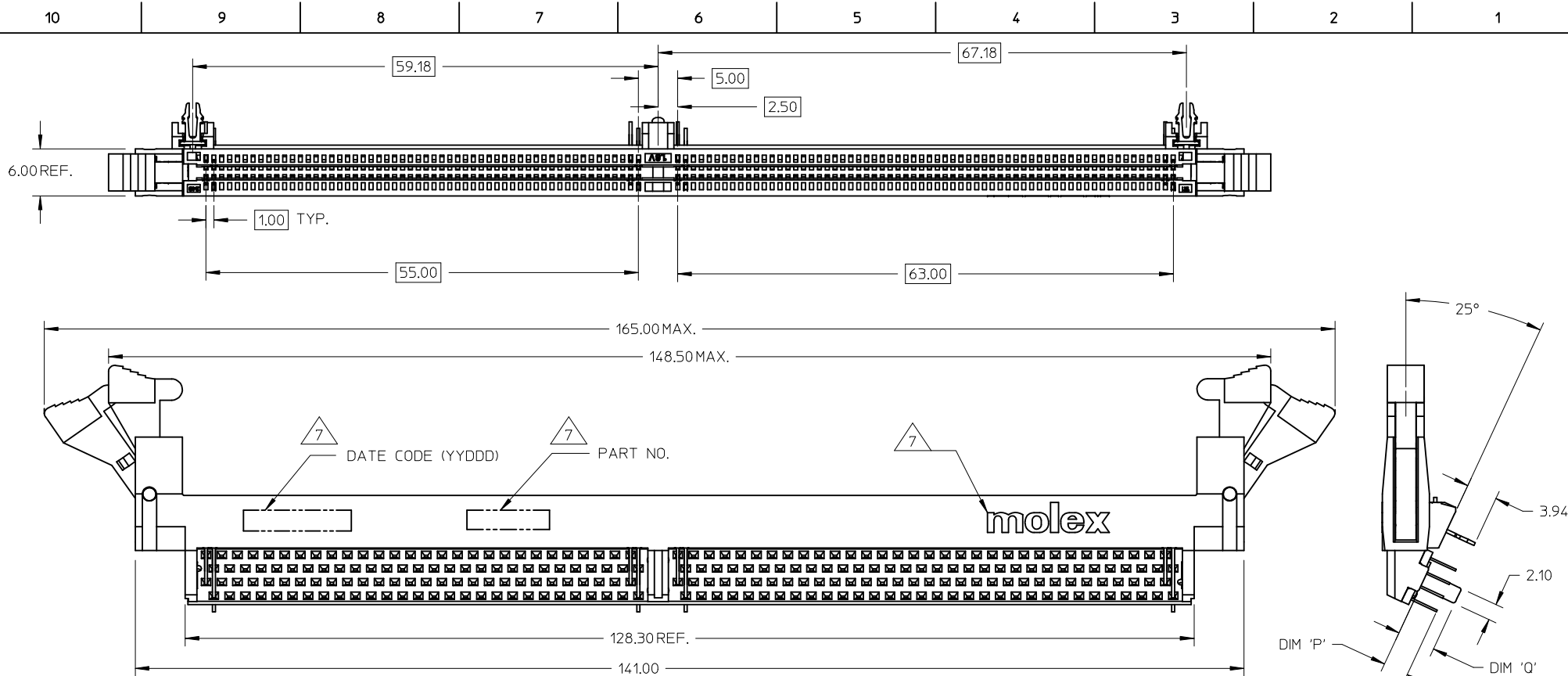
Material Info

Reference - Drawing Numbers

Product Specification	PS-87803-003
Sales Drawing	SD-87803-010

This document was generated on 04/09/2010

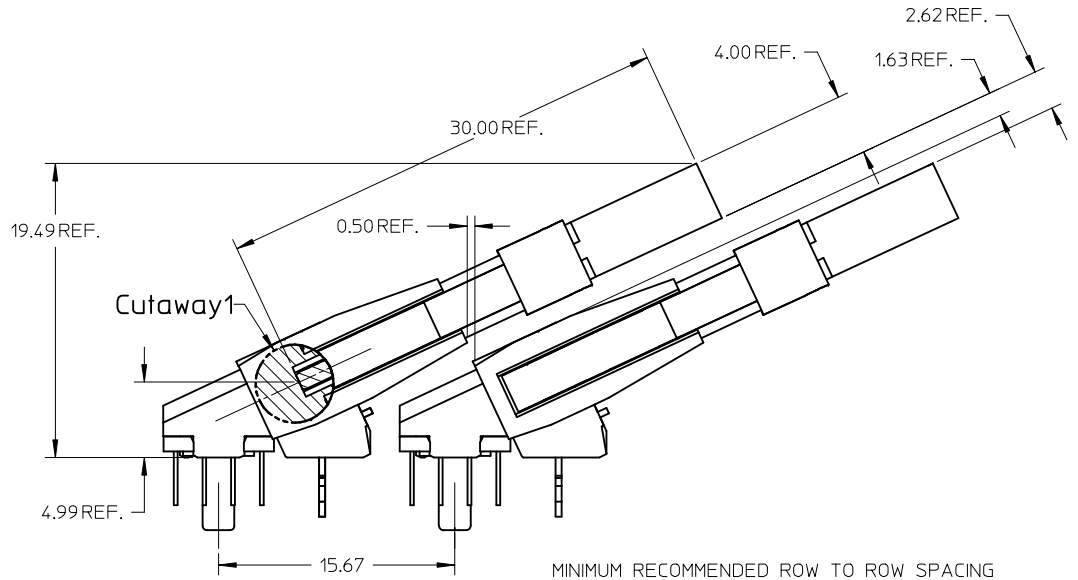
PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION



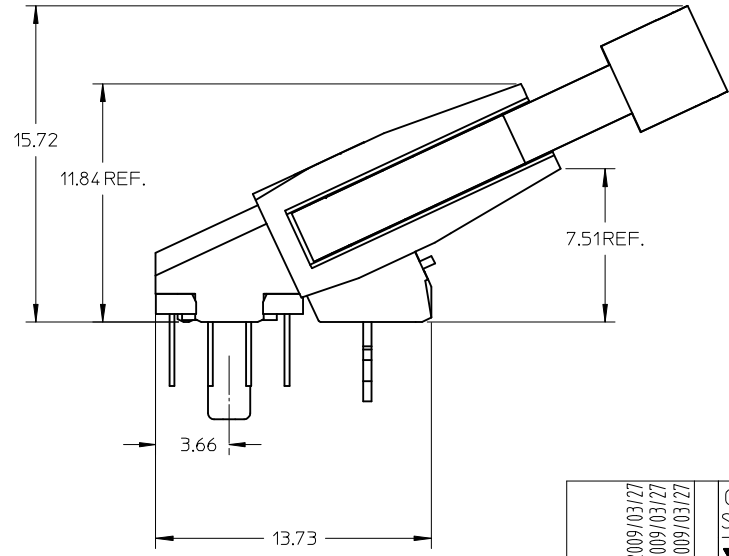
NOTES:

- MATERIALS : HOUSING AND BASEPLATE
 - LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
 - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
 - TERMINALS AND FORKLICK - COPPER ALLOY
- PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
- REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
- CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
- RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
- PRODUCT IS PACKED IN TRAY.
- MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
- CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

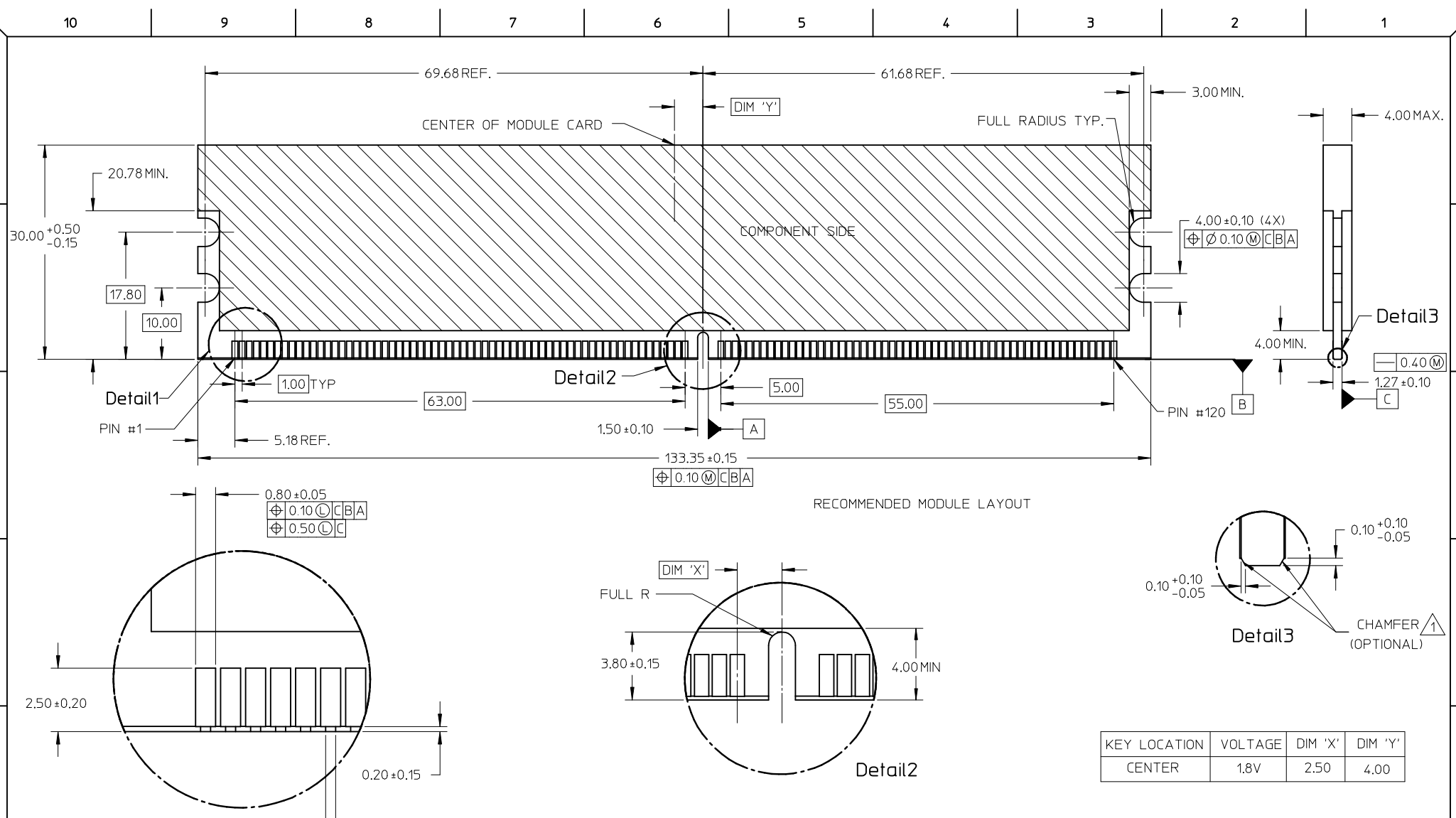
ADDED OPTION EC NO: S2009-0629 DRW:ACCTEH 2009/03/27 CHKD:CGTAN 2009/03/27 APPR:SHLENI 2009/03/27 B1	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	mm INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
		3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	CHECKED BY SRRAMESH	DATE 2004/03/26	MOLEX MOLEX INCORPORATED		
		1 PLACE ± --- ± ---	ANGULAR ± 5 °	APPROVED BY GGLEE	DATE 2004/03/26	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SD-87803-010	1 OF 5



MINIMUM RECOMMENDED ROW TO ROW SPACING
WHEN USING A 4.00MM THICK
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH 2009/03/27 CHKD: GGTAN 2009/03/27 APPR: SHLENI 2009/03/27	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		▼=0 ∇=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: MLONG DATE: 2004/03/25 CHECKED BY: SRRAMESH DATE: 2004/03/26 APPROVED BY: GGLEE DATE: 2004/03/26	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
		B1		SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-87803-010	SHEET NO.	2 OF 5	



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES :
 1 MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

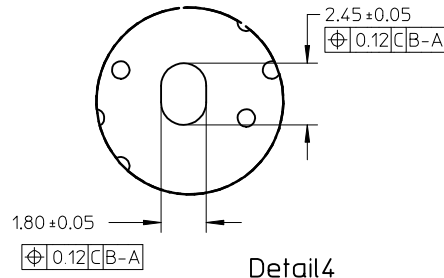
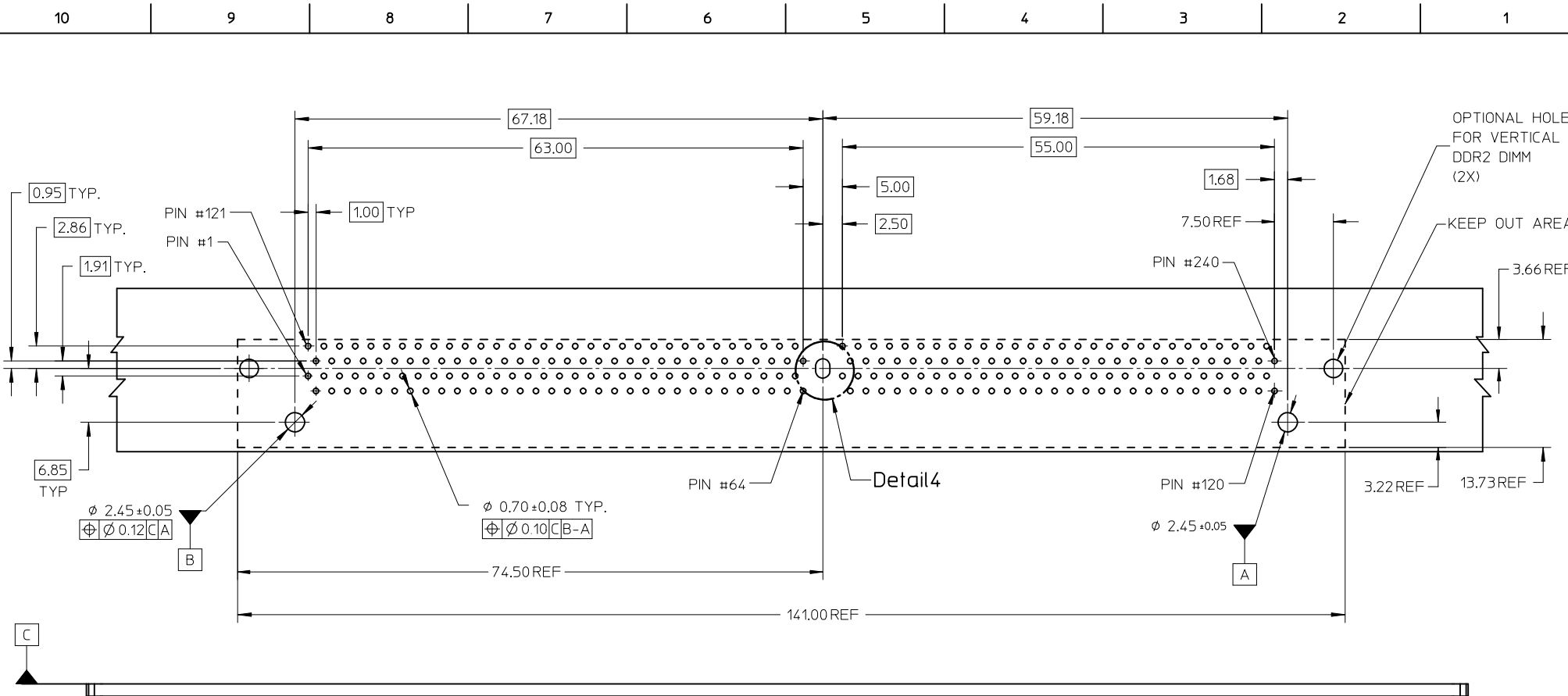
ADDED OPTION
 EC NO: S2009-0629
 DRW:NCCTEH
 CHKD:CGTAN
 APPR:SHLENI

REV	DESCRIPTION
B1	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ±---	±---
◻=0	3 PLACES ±---	±---
	2 PLACES ±0.25	±---
	1 PLACE ±---	±---
	ANGULAR ± 5 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
MLONG	2004/03/25
CHECKED BY	DATE
SRRAMESH	2004/03/26
APPROVED BY	DATE
GGLEE	2004/03/26
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	☉
TITLE		
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
MOLEX INCORPORATED		SHEET NO.
DOCUMENT NO.		3 OF 5
SD-87803-010		



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI	2009/03/27 2009/03/27 2009/03/27	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
					mm	INCH	MM ONLY	NTS		METRIC
					DRAWN BY		DATE	TITLE		
					MLONG		2004/03/25	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
				CHECKED BY		DATE	MOLEX INCORPORATED		DOCUMENT NO.	
				SRRAMESH		2004/03/26	SD-87803-010			
				APPROVED BY		DATE	SHEET NO.			
				GGLEE		2004/03/26	4 OF 5			
				MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
				SEE TABLE						

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38uM/ 15u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN, TIN (MATTE) OVER 1.27uM/ 50u" MIN NICKEL	NO
87803-0022							YES
87803-0012		3.18	4.83	2.36			NO
87803-0032							YES
87803-0052		4.00	3.18	NO			
87803-0062				YES			
87803-0102		2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL		NO
87803-0122							YES
87803-0112		3.18	4.83	2.36			NO
87803-0132							YES
87803-0152		4.00	3.18	NO			
87803-0162				YES			

ADDED OPTION EC NO: S2009-0629 DRWN: CCTE CH'KD: GTAN APPR: SILENI 2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	$\nabla = 0$ $\triangle = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC		
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY: MLONG DATE: 2004/03/25 CHECKED BY: SRRAMESH DATE: 2004/03/26 APPROVED BY: GGLEE DATE: 2004/03/26 MATERIAL NO.	TITLE	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
	REV: B1		SEE TABLE	MOLEX INCORPORATED DOCUMENT NO. SD-87803-010		SHEET NO. 5 OF 5	